

# Electronic Filing System (EFS) Data **Electronic Patent Application Submission USPTO Use Only**

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Application ID:

10665651

Title of Invention:

SEMICONDUCTOR PACKAGE AND

THIN AND HEAT RADIANT

METHOD FOR MANUFACTURING

First Named Inventor:

Jae Ku

Domestic/Foreign Application: Domestic Application

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**Submission Type:** 

Information Disclosure

Statement

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6079

Attorney Docket Number:

AMKOR041G

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### **TRANSMITTAL**

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention

THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING

Application Number:

10/665651

Date:

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First Named Applicant:

Jae Hun Ku

Confirmation Number:

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Attorney Docket Number: AMKOR041G

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I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.

Submitted by:	Elec. Sign.	Sign. Capacity	
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney	

Documents being submitted

**Files** 

us-ids

ids6-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



## **ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v18 Stylesheet Version v18.0

> Title of Invention

THIN AND HEAT RADIANT SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING

**Application Number:** 

10/665651

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6079

First Named Applicant:

Jae Ku

Attorney Docket Number: AMKOR041G

Art Unit:

2811

Search string:

( 6395578 or 6400004 or 6410979 or 6414385 or 6420779 or 6429508 or 6437429 or 6444499 or 6448633 or 6452279 or 6464121 or 6476469 or 6476474 or 6482680 or 6498099 or 6498392 or 6507096 or 6507120 or 6534849 or 6559525

or 6566168 ).pn.

#### **US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6395578	2002-05-28	SHIN ET AL.			
	2	6400004	2002-06-04	FAN ET AL.			
	3	6410979	2002-06-25	ABE			
	4	6414385	2002-07-02	HUANG ET AL.			
	5	6420779	2002-07-16	SHARMA ET AL.			
	6	6429508	2002-08-06	GANG			
	7	6437429	2002-08-20	SU ET AL.			
	8	6444499	2002-09-03	SWISS ET AL.			
	9	6448633	2002-09-10	YEE ET AL.			
	10	6452279	2002-09-17	SHIMODA			
	11	6464121	2002-10-15	REIJNDERS			•
	12	6476469	2002-11-05	HUNG ET AL.			
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	14	6482680	2002-11-19	KHOR ET AL.			
	15	6498099	2002-12-24	MCLELLAN ET AL.			

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16	6498392	2002-12-24	AZUMA
17	6507096	2003-01-14	GANG
18	6507120	2003-01-14	LO ET AL.
19	6534849	2003-03-18	GANG
20	6559525	2003-05-06	HUANG
21	6566168	2003-05-20	GANG

## Signature

Examiner Name	Date